CDC208 DUAL 1-LINE TO 4-LINE CLOCK DRIVER WITH 3-STATE OUTPUTS SCAS109F – APRIL 1990 – REVISED OCTOBER 1998

		30A31031 - AI KIE 1330 - KEVIC	
•	Low-Skew Propagation Delay Specifications for Clock-Driver	DW PACKAGE (TOP VIEW)	
•	Applications TTL-Compatible Inputs and CMOS-Compatible Outputs	1Y2 1 20 1Y1 1Y3 2 19 1A	
•	Flow-Through Architecture Optimizes PCB Layout	1Y4 3 18 1 <u>0E1</u> GND 4 17 10E2 GND 5 16 V _{CC}	
•	Center-Pin V _{CC} and GND Pin Configurations Minimize High-Speed Switching Noise	GND 6 15 V _{CC} GND 7 14 2A 2Y1 8 13 2OE1	
•	<i>EPIC</i> ™ (Enhanced-Performance Implanted CMOS) 1-μm Process	2Y2 9 12 2OE2 2Y3 10 11 2Y4	
•	500-mA Typical Latch-Up Immunity at 125°C		

 Package Options Include Plastic Small-Outline (DW)

description

The CDC208 contains dual clock-driver circuits that fanout one input signal to four outputs with minimum skew for clock distribution (see Figure 2). The device also offers two output-enable ($\overline{OE1}$ and $\overline{OE2}$) inputs for each circuit that can force the outputs to be disabled to a high-impedance state or to a high- or low-logic level independent of the signal on the respective A input.

Skew parameters are specified for a reduced temperature and voltage range common to many applications.

The CDC208 is characterized for operation from -40°C to 85°C.

_		FUNC		ABLES		
	INPUTS			OUT	PUTS	
10E1	1Y3	1Y4				
L	L	L	L	L	L	L
L	L	Н	н	Н	Н	н
L	н	Х	L	L	L	L
Н	L	Х	н	н	Н	н
н	н	Х	Z	Z	Ζ	Z

	INPUTS		OUTPUTS						
20E1	OE1 20E2 2A		2Y1	2Y2	2Y3	2Y4			
L	L	L	L	L	L	L			
L	L	Н	Н	Н	Н	Н			
L	Н	Х	L	L	L	L			
н	L	Х	Н	н н		Н			
н	Н	Х	Z	Z	Ζ	Z			

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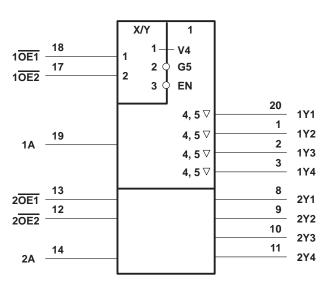
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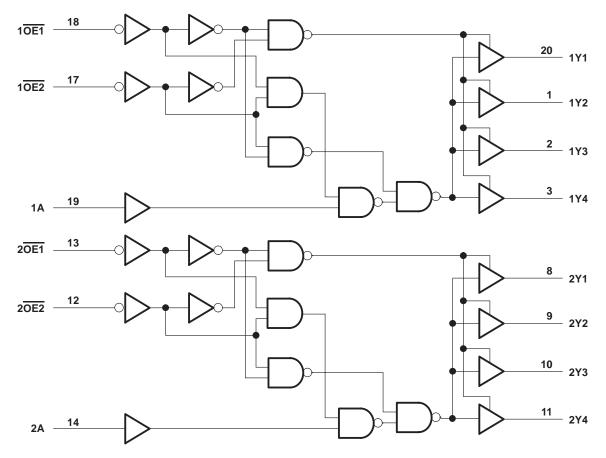
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logic symbol[†]



[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

2. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

recommended operating conditions

		MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
VI	Input voltage	0		VCC	V
ЮН	High-level output current			-24	mA
IOL	Low-level output current			24	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	0		10	ns/V
fclock	Input clock frequency			60	MHz
TA	Operating free-air temperature	-40		85	°C



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

			Т	₄ = 25°C	;			
PARAMETER	TEST CONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
	10	4.5 V	4.4			4.4		
	I _{OH} = -50 μA	5.5 V	5.4			5.4		
VOH	1 24 mA	4.5 V	3.94			3.8		V
	I _{OH} = -24 mA	5.5 V	4.94			4.8		
	$I_{OH} = -75 \text{ mA}^{\dagger}$	5.5 V				3.85		
		4.5 V			0.1		0.1	
	I _{OL} = 50 μA	5.5 V			0.1		0.1	V
VOL		4.5 V			0.36		0.44	
	$I_{OL} = 24 \text{ mA}$	5.5 V			0.36		0.44	
	$I_{OL} = 75 \text{ mA}^{\dagger}$	5.5 V					1.65	
l	$V_{I} = V_{CC} \text{ or } GND$	5.5 V			±0.1		±1	μA
IOZ	$V_{O} = V_{CC}$ or GND	5.5 V			±0.5		±5	μA
ICC	$V_{I} = V_{CC} \text{ or } GND, \qquad I_{O} = 0$	5.5 V			8		80	μA
ΔI_{CC}^{\ddagger}	One input at 3.4 V, Other inputs at V _{CC} or GND	5.5 V			0.9		1	mA
Ci	$V_{I} = V_{CC}$ or GND	5 V		4				pF
Co	$V_{O} = V_{CC}$ or GND	5 V		10				pF

[†] Not more than one output should be tested at a time, and the duration of the test should not exceed 10 ms.

[‡]This is the increase in supply current for each input that is at one of the specified TTL voltage levels rather than 0 V or V_{CC}.



switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V \pm 0.5 V (unless otherwise noted) (see Figure 1)

	1							
DADAMETED	FROM	то	T,	₄ = 25°C	;		MAX	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN		
^t PLH	14 and 24	1 m / 1	5.3	8.5	10.9	5.3	11.7	
^t PHL	1A and 2A	Any Y	3.6	7.7	11	3.6	11.5	ns
^t PLH	10E1, 10E2, and	1 m / 1	4.7	8.5	11.7	4.7	12.8	
^t PHL	20E1, 20E2	Any Y	4.4	8.4	11.3	4.4	12.4	ns
^t PZH	10E2 or 20E2	A	4.4	8.1	11.3	4.4	12.4	
^t PZL	10E1 or 20E1	Any Y	5	9.6	13.3	5	14.9	ns
^t PHZ	10E2 or 20E2	Anvill	4.2	7.4	9.3	4.2	10.2	
^t PLZ	10E1 or 20E1	Any Y	5.4	7.5	9.2	5.4	9.9	ns

switching characteristics, V_{CC} = 5 V \pm 0.25 V, T_A = 25°C to 70°C (see Note 3 and Figures 1 and 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		MAX	UNIT
^t PLH		Arres	6.6	10.2	
^t PHL	1A and 2A	Any Y	6.6	9.8	ns
^t sk(o)	1A and 2A	Any Y		1	ns

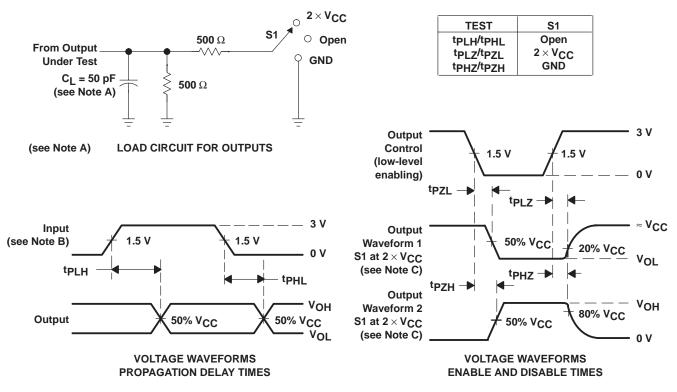
NOTE 3: All specifications are valid only for all outputs switching simultaneously and in phase.

operating characteristics, V_{CC} = 5 V, T_A = 25°C

	PARAMETER	TEST CONDITIONS	TYP	UNIT	
<u> </u>	Power dissinction conscitance per bank	Outputs enabled	Cı = 50 pF. f = 1 MHz	96	~
Cpd	Power dissipation capacitance per bank	Outputs disabled	$C_L = 50 \text{ pF}, \text{ f} = 1 \text{ MHz}$	12	pF



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PARAMETER MEASUREMENT INFORMATION

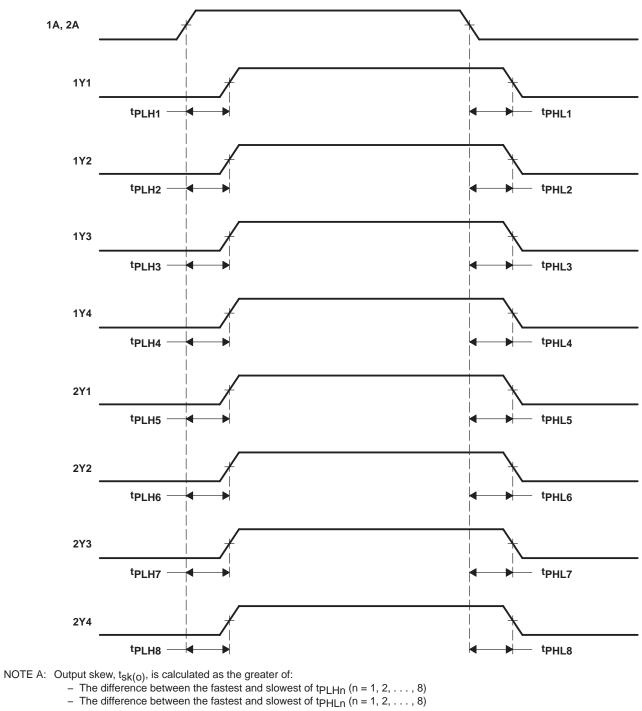
NOTES: A. CL includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 3 ns, t_f \leq 3 ns. For testing pulse duration: $t_r = t_f = 1$ to 3 ns. Pulse polarity can be either high-to-low-to-high or low-to-high-to-low.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

Figure 1. Load Circuit and Voltage Waveforms



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PARAMETER MEASUREMENT INFORMATION

Figure 2. Waveforms for Calculation of tsk(o)

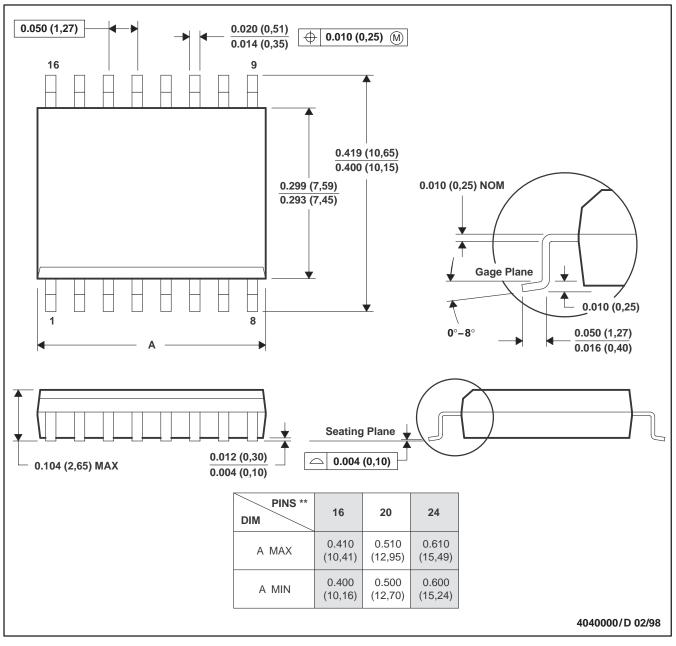


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MECHANICAL INFORMATION

PLASTIC SMALL-OUTLINE PACKAGE





NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
CDC208DBLE	OBSOLETE	SSOP	DB	20		TBD	Call TI	Call TI
CDC208DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC208DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC208DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC208DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC208N	OBSOLETE	PDIP	Ν	20		TBD	Call TI	Call TI
CDC208NS	ACTIVE	SO	NS	20	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC208NSG4	ACTIVE	SO	NS	20	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC208NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CDC208NSRG4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

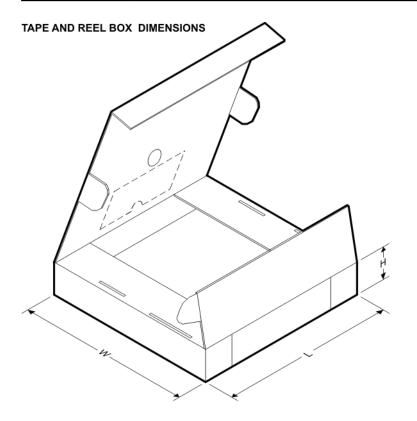


*A	Il dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	CDC208DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
	CDC208NSR	SO	NS	20	2000	330.0	24.4	8.2	13.0	2.5	12.0	24.0	Q1



PACKAGE MATERIALS INFORMATION

5-Aug-2008



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CDC208DWR	SOIC	DW	20	2000	346.0	346.0	41.0
CDC208NSR	SO	NS	20	2000	346.0	346.0	41.0

MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 \bigcirc Gage Plane ₽ 0,25 7 1 1,05 0,55 0-10 Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS ** 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G**)

14-PINS SHOWN

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AC.



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